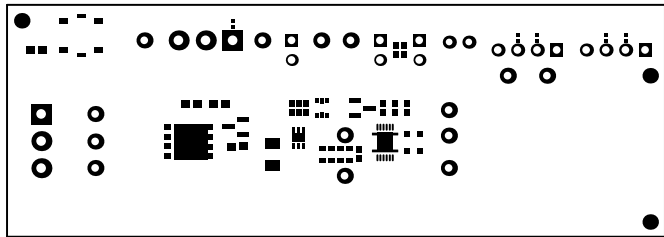
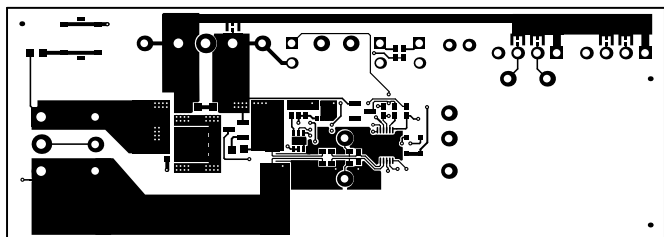


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR532	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 1/27/2016 2:55:40 PM	TEXAS INSTRUMENTS	

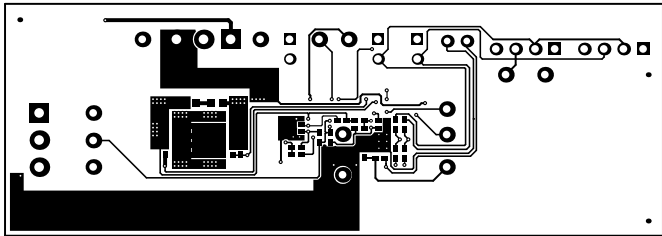


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR532	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 1/27/2016 2:55:43 PM	TEXAS INSTRUMENTS	

USB-CTK-DK-EVM

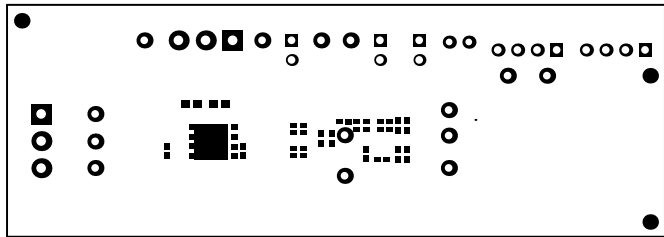


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR532	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 1/27/2016 2:55:45 PM	TEXAS INSTRUMENTS	

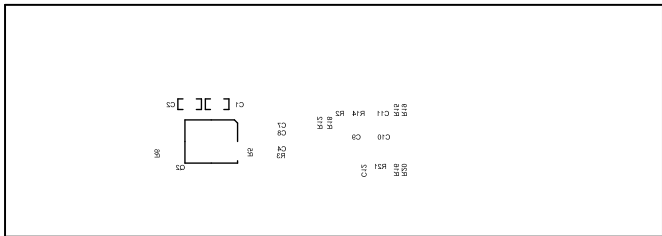


SUN REV: Not In VersionControl

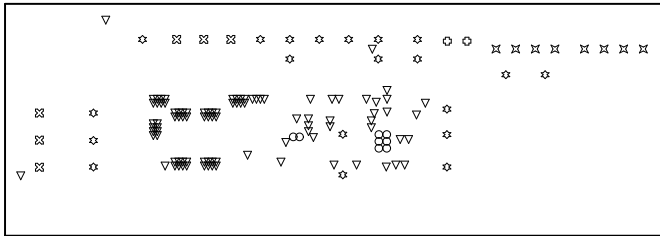
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR532	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 1/27/2016 2:55:47 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR532	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 1/27/2016 2:55:50 PM	TEXAS INSTRUMENTS	



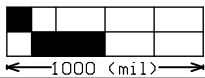
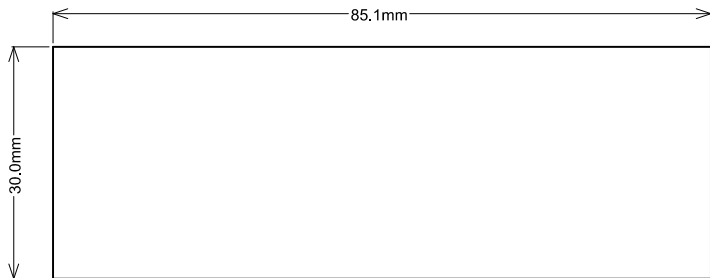
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR532	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 1/27/2016 2:55:52 PM	TEXAS INSTRUMENTS	



Symbol	Hit Count	Tool Size	Plated	Hole Type
○	8	7.874mil (0.2mm)	PTH	Round
▽	94	10mil (0.254mm)	PTH	Round
⊙	2	35mil (0.889mm)	PTH	Round
*	20	40mil (1.016mm)	PTH	Round
⊗	8	40.157mil (1.02mm)	PTH	Round
⊗	6	50mil (1.27mm)	PTH	Round
	138 Total			

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR532	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 1/27/2016 2:55:54 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR532	REV: B	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 1/27/2016 2:55:56 PM	TEXAS INSTRUMENTS	

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